

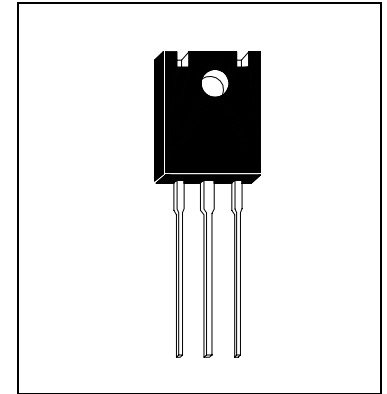


HTL295D

PNP EPITAXIAL PLANAR TRANSISTOR

Description

The HTL295D is designed for high voltage low power switching applications especially for use in telephone and telecommunication circuits.



Absolute Maximum Ratings

- Maximum Temperatures
 - Storage Temperature -55 ~ +150 °C
 - Junction Temperature 150 °C Maximum
- Maximum Power Dissipation
 - Total Power Dissipation (Ta=25°C) 1.5 W
- Maximum Voltages and Currents (Ta=25°C)
 - VCBO Collector to Base Voltage -500 V
 - VCEO Collector to Emitter Voltage -500 V
 - VEBO Emitter to Base Voltage -6 V
 - IC Collector Current -250 mA

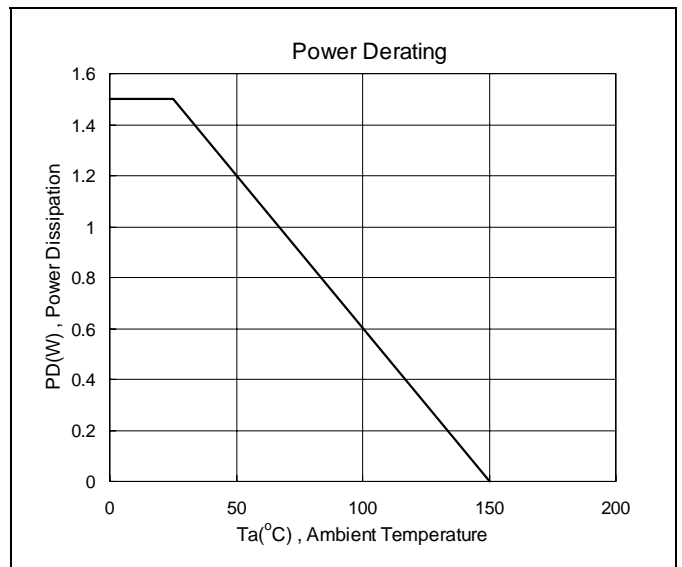
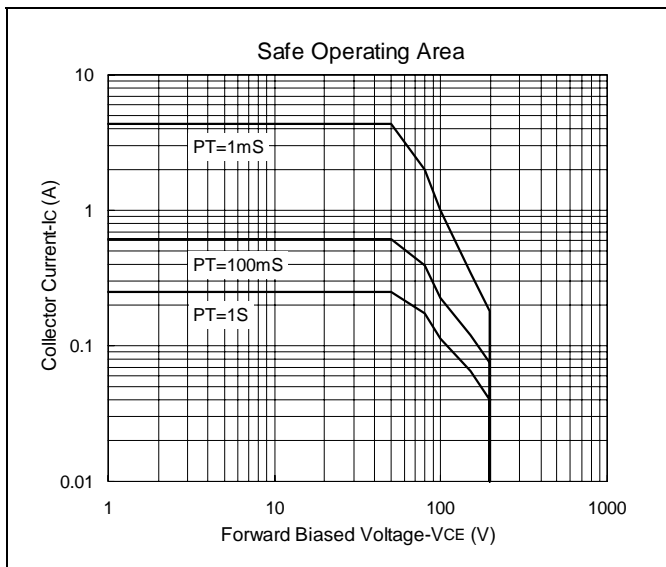
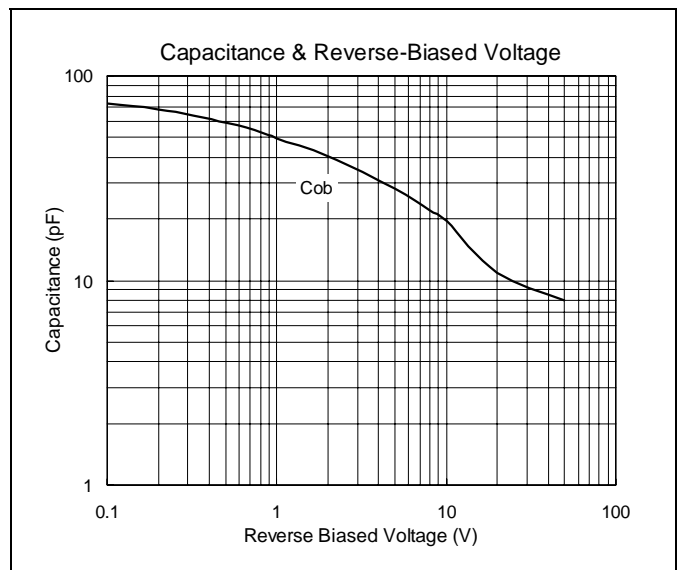
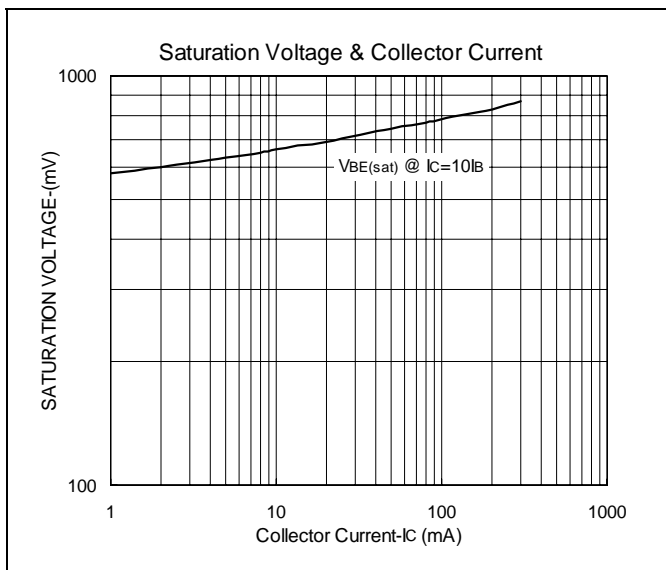
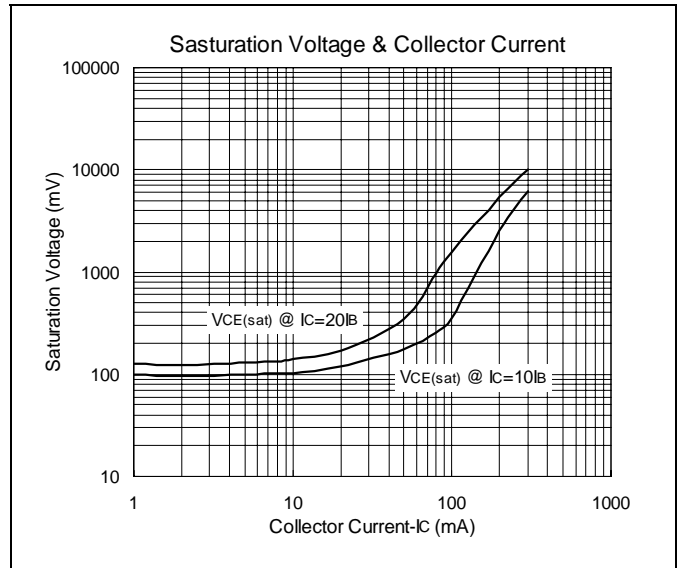
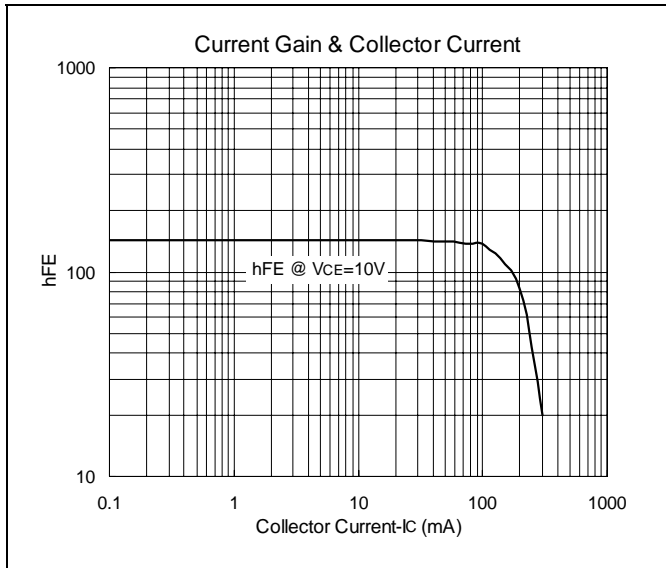
Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-500	-	-	V	IC=-100uA, IE=0
BVCEO	-500	-	-	V	IC=-1mA, IB=0
BVEBO	-6	-	-	V	IE=-10uA
ICBO	-	-	-1	uA	VCB=-500V, IE=0
ICES	-	-	-10	uA	VCE=-500V, IB=0
IEBO	-	-	-0.2	uA	VEB=-6V, IC=0
*VCE(sat)1	-	-	-500	mV	IC=-10mA, IB=-1mA
*VCE(sat)2	-	-	-2	V	IC=-50mA, IB=-5mA
*VCE(sat)3	-	-	-3	V	IC=-80mA, IB=-4mA
*VBE(sat)	-	-	-750	mV	IC=-10mA, IB=-1mA
*hFE1	50	-	-		VCE=-10V, IC=-1mA
*hFE2	60	-	250		VCE=-10V, IC=-20mA
*hFE3	50	-	-		VCE=-10V, IC=-80mA
fT	10	-	-	MHz	VCE=-20V, IE=-10mA, f=1MHz
Cob	-	-	30	pF	VCB=-20V, f=1MHz, IE=0

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%

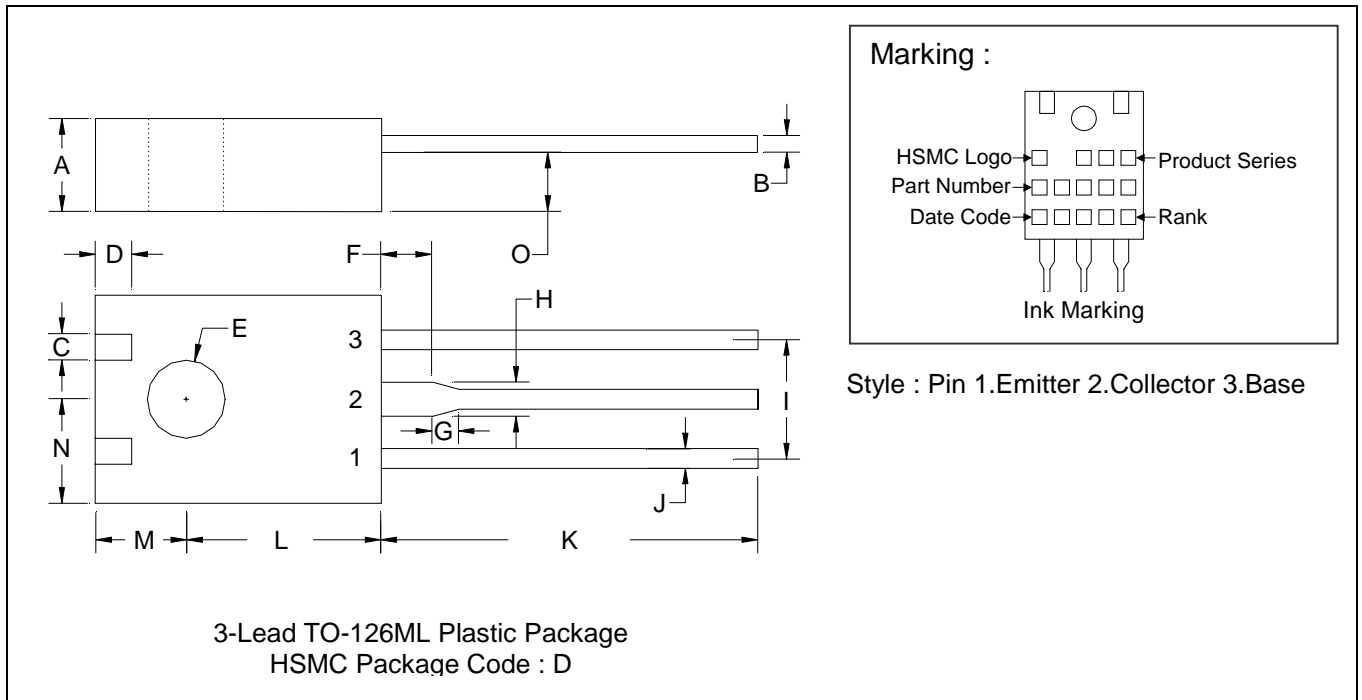


Characteristics Curve





TO-126ML Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1356	0.1457	3.44	3.70	I	-	*0.1795	-	*4.56
B	0.0170	0.0272	0.43	0.69	J	0.0268	0.0331	0.68	0.84
C	0.0344	0.0444	0.87	1.12	K	0.5512	0.5906	14.00	15.00
D	0.0501	0.0601	1.27	1.52	L	0.2903	0.3003	7.37	7.62
E	0.1131	0.1231	2.87	3.12	M	0.1378	0.1478	3.50	3.75
F	0.0737	0.0837	1.87	2.12	N	0.1525	0.1625	3.87	4.12
G	0.0294	0.0494	0.74	1.25	O	0.0740	0.0842	1.88	2.14
H	0.0462	0.0562	1.17	1.42					

Notes : 1.Dimension and tolerance based on our Spec. dated Mar. 6,1995.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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